PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data		
1.1 Company STMicroelectronics International N.V		STMicroelectronics International N.V
1.2 PCN No.		ADG/18/10757
1.3 Title of PCN		IGBT Planar Discrete and IPM Front-end Line relocation to Ang Mo Kio (Singapore) - INDUSTRIAL
1.4 Product Category		IGBTs
1.5 Issue date		2018-03-01

2. PCN Team		
2.1 Contact supplier		
2.1.1 Name	MARSHALL DAVE	
2.1.2 Phone		
2.1.3 Email	dave.marshall@st.com	
2.2 Change responsibility		
2.2.1 Product Manager	Maurizio GIUDICE	
2.1.2 Marketing Manager	Anna MOTTESE	
2.1.3 Quality Manager	Vincenzo MILITANO	

3. Change			
3.1 Category	3.2 Type of change	3.3 Manufacturing Location	
	Line transfer for a full process or process brick (process step, control plan, recipes) from one site to another site: Wafer fabrication	Ang Mo Kio (Singapore) Shenzhen (China) / Tongfu Microelectronics (China)	

4. Description of change			
Old New			
	IGBT Planar Technology is manufactured in the 6" wafer line of Catania (Italy)	IGBT Planar Technology is manufactured in the 6" wafer line of Ang Mo Kio (Singapore)	
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	No impact		

5. Reason / motivation for change		
5.1 Motivation	Front-end & Testing Relocation	
5.2 Customer Benefit	MANUFACTURING FLEXIBILITY	

6. Marking of parts / traceability of change		
6.1 Description	by the digit 6 as front-end code, internal code (Finished Good) and Q.A. number.	

7. Timing / schedule	
7.1 Date of qualification results	2018-02-23
7.2 Intended start of delivery	2018-05-21
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation			
8.1 Description	10757 Rel01-18.pdf		
8.2 Qualification report and qualification results		Issue Date	2018-03-01

9. Attachments (additional documentations)

10757 Public product.pdf 10757 IGBT Planar Front-end Line relocation to Ang Mo Kio (Singapore) - INDUSTRIAL.pdf 10757 Rel01-18.pdf

10. Affected parts			
10. 1 Current		10.2 New (if applicable)	
10.1.1 Customer Part No 10.1.2 Supplier Part No		10.1.2 Supplier Part No	
	STGIPQ3H60T-HL		
	STGIPQ3H60T-HZ		

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